

## P0850ATFS-VB Datasheet

### N-Channel 650V (D-S) Power MOSFET

#### PRODUCT SUMMARY

|                                    |                        |      |
|------------------------------------|------------------------|------|
| $V_{DS}$ (V) at $T_J$ max.         | 650                    |      |
| $R_{DS(on)}$ at 25 °C ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ | 0.82 |
| $Q_g$ max. (nC)                    | 57                     |      |
| $Q_{gs}$ (nC)                      | 4.0                    |      |
| $Q_{gd}$ (nC)                      | 5.4                    |      |
| Configuration                      | Single                 |      |

#### FEATURES

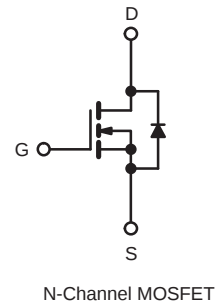
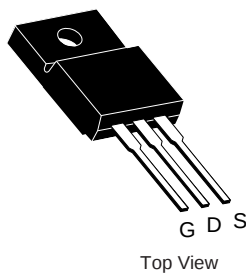
- Low figure-of-merit (FOM)  $R_{DS(on)} \times Q_g$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Ultra low gate charge ( $Q_g$ )
- Avalanche energy rated (UIS)



#### APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial

TO-220 FULLPAK



#### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ °C}$ , unless otherwise noted)

| PARAMETER                                                 |                         |                         | SYMBOL                            | LIMIT        | UNIT |
|-----------------------------------------------------------|-------------------------|-------------------------|-----------------------------------|--------------|------|
| Drain-Source Voltage                                      |                         |                         | V <sub>DS</sub>                   | 650          | V    |
| Gate-Source Voltage                                       |                         |                         | V <sub>GS</sub>                   | ± 30         |      |
| Continuous Drain Current (T <sub>J</sub> = 150 °C)        | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 25 °C  | I <sub>D</sub>                    | 10           | A    |
|                                                           |                         | T <sub>C</sub> = 100 °C |                                   | 8            |      |
| Pulsed Drain Current <sup>a</sup>                         |                         |                         | I <sub>DM</sub>                   | 35           |      |
| Linear Derating Factor                                    |                         |                         |                                   | 1.67/1.5/0.3 | W/°C |
| Single Pulse Avalanche Energy <sup>b</sup>                |                         |                         | E <sub>AS</sub>                   | 86           | mJ   |
| Maximum Power Dissipation                                 |                         |                         | P <sub>D</sub>                    | 178/156/53   | W    |
| Operating Junction and Storage Temperature Range          |                         |                         | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150  | °C   |
| Drain-Source Voltage Slope                                | T <sub>J</sub> = 125 °C |                         | dV/dt                             | 50           | V/ns |
| Reverse Diode dV/dt <sup>d</sup>                          |                         |                         |                                   | 4.5          |      |
| Soldering Recommendations (Peak Temperature) <sup>c</sup> | for 10 s                |                         |                                   | 300          | °C   |

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.  
 b.  $V_{DS} = 50\text{ V}$ , starting  $T_J = 25\text{ °C}$ ,  $L = 28.2\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 3.5\text{ A}$ .  
 c. 1.6 mm from case.  
 d.  $I_{SD} \leq I_D$ ,  $dI/dt = 100\text{ A}/\mu\text{s}$ , starting  $T_J = 25\text{ °C}$ .

**THERMAL RESISTANCE RATINGS**

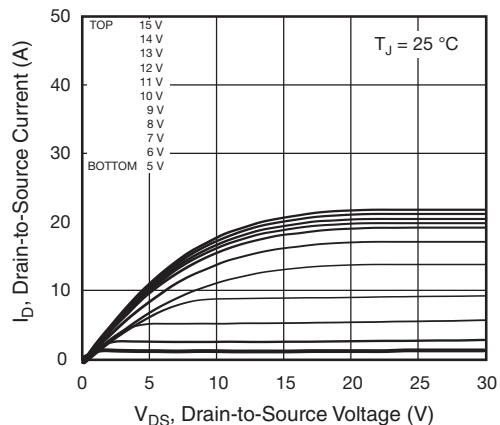
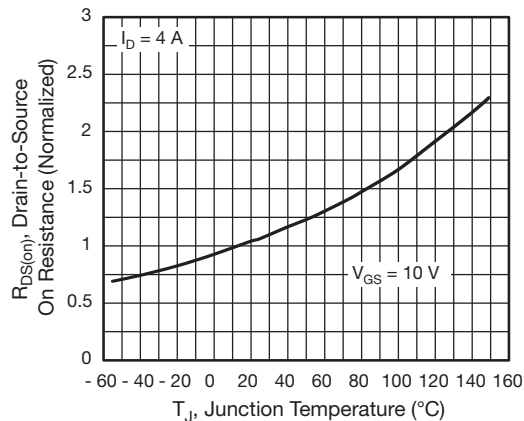
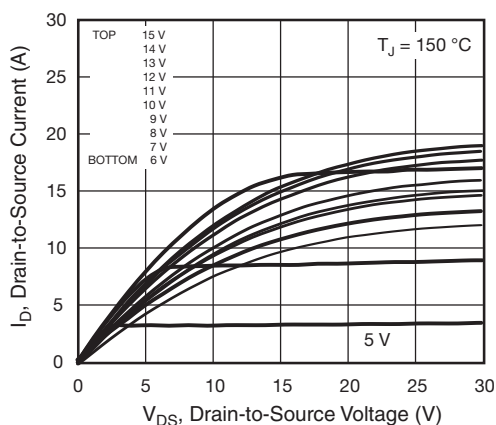
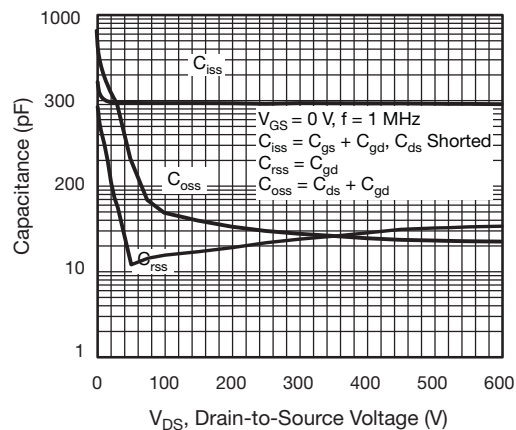
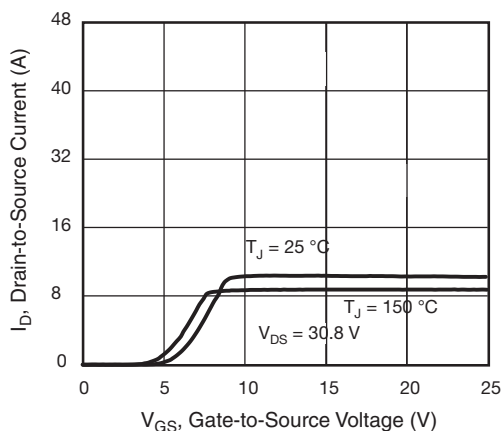
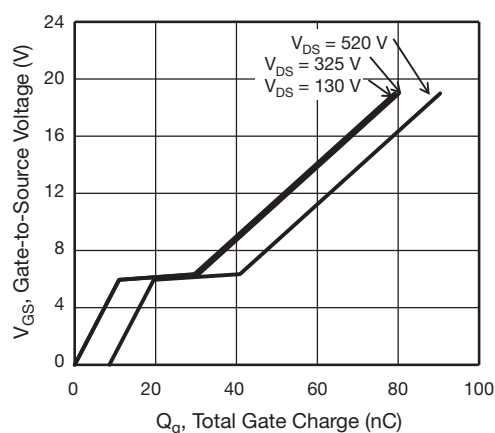
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT |
|----------------------------------|------------|------|------|------|
| Maximum Junction-to-Ambient      | $R_{thJA}$ | -    | 63   | °C/W |
| Maximum Junction-to-Case (Drain) | $R_{thJC}$ | -    | 0.6  |      |

**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

| PARAMETER                                                 | SYMBOL              | TEST CONDITIONS                                                                                                                                         |                                           | MIN. | TYP. | MAX.      | UNIT          |
|-----------------------------------------------------------|---------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------------------|------|------|-----------|---------------|
| Static                                                    |                     |                                                                                                                                                         |                                           |      |      |           |               |
| Drain-Source Breakdown Voltage                            | $V_{DS}$            | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$                                                                                                     |                                           | 650  | -    | -         | V             |
| $V_{DS}$ Temperature Coefficient                          | $\Delta V_{DS}/T_J$ | Reference to 25 °C, $I_D = 1\text{ mA}$                                                                                                                 |                                           | -    | 0.65 | -         | V/°C          |
| Gate-Source Threshold Voltage (N)                         | $V_{GS(th)}$        | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$                                                                                                         |                                           | 2    | -    | 4         | V             |
| Gate-Source Leakage                                       | $I_{GSS}$           | $V_{GS} = \pm 20\text{ V}$                                                                                                                              |                                           | -    | -    | $\pm 100$ | nA            |
|                                                           |                     | $V_{GS} = \pm 30\text{ V}$                                                                                                                              |                                           | -    | -    | $\pm 1$   | $\mu\text{A}$ |
| Zero Gate Voltage Drain Current                           | $I_{DSS}$           | $V_{DS} = 650\text{ V}, V_{GS} = 0\text{ V}$                                                                                                            |                                           | -    | -    | 1         | $\mu\text{A}$ |
|                                                           |                     | $V_{DS} = 520\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^{\circ}\text{C}$                                                                         |                                           | -    | -    | 10        |               |
| Drain-Source On-State Resistance                          | $R_{DS(on)}$        | $V_{GS} = 10\text{ V}$                                                                                                                                  | $I_D = 4\text{ A}$                        | -    | 0.82 | -         | $\Omega$      |
| Forward Transconductance                                  | $g_{fs}$            | $V_{DS} = 30\text{ V}, I_D = 4\text{ A}$                                                                                                                |                                           | -    | 16   | -         | S             |
| Dynamic                                                   |                     |                                                                                                                                                         |                                           |      |      |           |               |
| Input Capacitance                                         | $C_{iss}$           | $V_{GS} = 0\text{ V},$<br>$V_{DS} = 100\text{ V},$<br>$f = 1\text{ MHz}$                                                                                |                                           | -    | 1900 | -         | pF            |
| Output Capacitance                                        | $C_{oss}$           |                                                                                                                                                         |                                           | -    | 400  | -         |               |
| Reverse Transfer Capacitance                              | $C_{rss}$           |                                                                                                                                                         |                                           | -    | 240  | -         |               |
| Effective Output Capacitance, Energy Related <sup>a</sup> | $C_{o(er)}$         | $V_{DS} = 0\text{ V to } 520\text{ V}, V_{GS} = 0\text{ V}$                                                                                             |                                           | -    | 45   | -         |               |
| Effective Output Capacitance, Time Related <sup>b</sup>   | $C_{o(tr)}$         |                                                                                                                                                         |                                           | -    | 62   | -         |               |
| Total Gate Charge                                         | $Q_g$               | $V_{GS} = 10\text{ V}$                                                                                                                                  | $I_D = 4\text{ A}, V_{DS} = 520\text{ V}$ | -    | 40   | 57        | nC            |
| Gate-Source Charge                                        | $Q_{gs}$            |                                                                                                                                                         |                                           | -    | 4.0  | -         |               |
| Gate-Drain Charge                                         | $Q_{gd}$            |                                                                                                                                                         |                                           | -    | 5.4  | -         |               |
| Turn-On Delay Time                                        | $t_{d(on)}$         | $V_{DD} = 520\text{ V}, I_D = 4\text{ A},$<br>$V_{GS} = 10\text{ V}, R_g = 9.1\text{ }\Omega$                                                           |                                           | -    | 25   | -         | ns            |
| Rise Time                                                 | $t_r$               |                                                                                                                                                         |                                           | -    | 55   | -         |               |
| Turn-Off Delay Time                                       | $t_{d(off)}$        |                                                                                                                                                         |                                           | -    | 70   | -         |               |
| Fall Time                                                 | $t_f$               |                                                                                                                                                         |                                           | -    | 40   | -         |               |
| Gate Input Resistance                                     | $R_g$               | $f = 1\text{ MHz}, \text{open drain}$                                                                                                                   |                                           | -    | 3.5  | -         | $\Omega$      |
| Drain-Source Body Diode Characteristics                   |                     |                                                                                                                                                         |                                           |      |      |           |               |
| Continuous Source-Drain Diode Current                     | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode<br> |                                           | -    | -    | 7         | A             |
| Pulsed Diode Forward Current                              | $I_{SM}$            |                                                                                                                                                         |                                           | -    | -    | 18        |               |
| Diode Forward Voltage                                     | $V_{SD}$            | $T_J = 25\text{ }^{\circ}\text{C}, I_S = 4\text{ A}, V_{GS} = 0\text{ V}$                                                                               |                                           | -    | -    | 1.5       | V             |
| Reverse Recovery Time                                     | $t_{rr}$            | $T_J = 25\text{ }^{\circ}\text{C}, I_F = I_S = 4\text{ A},$<br>$dI/dt = 100\text{ A}/\mu\text{s}, V_R = 400\text{ V}$                                   |                                           | -    | 190  | -         | ns            |
| Reverse Recovery Charge                                   | $Q_{rr}$            |                                                                                                                                                         |                                           | -    | 2.3  | -         | $\mu\text{C}$ |
| Reverse Recovery Current                                  | $I_{RRM}$           |                                                                                                                                                         |                                           | -    | 10   | -         | A             |

**Notes**

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .  
 b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**

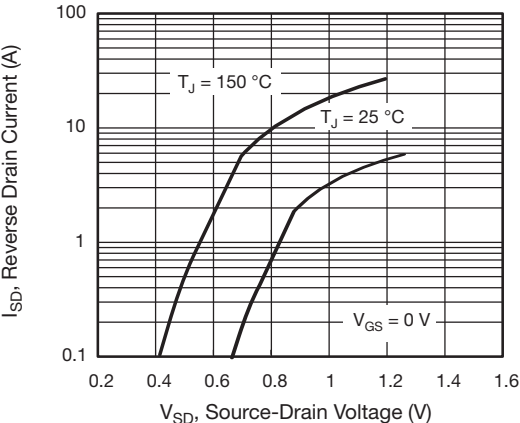


Fig. 7 - Typical Source-Drain Diode Forward Voltage

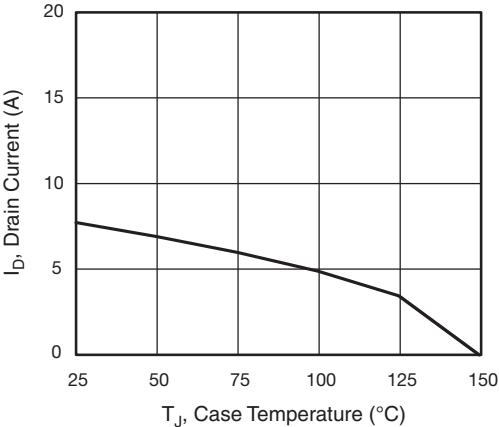


Fig. 9 - Maximum Drain Current vs. Case Temperature

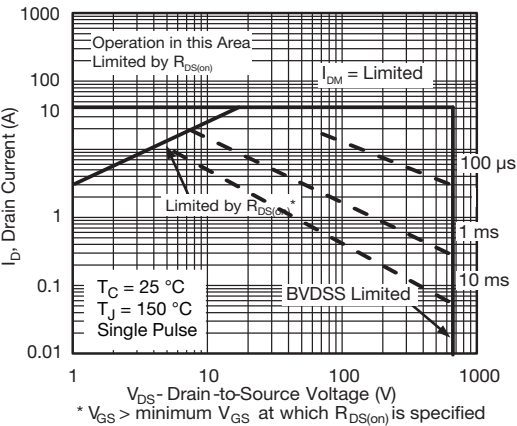


Fig. 8 - Maximum Safe Operating Area

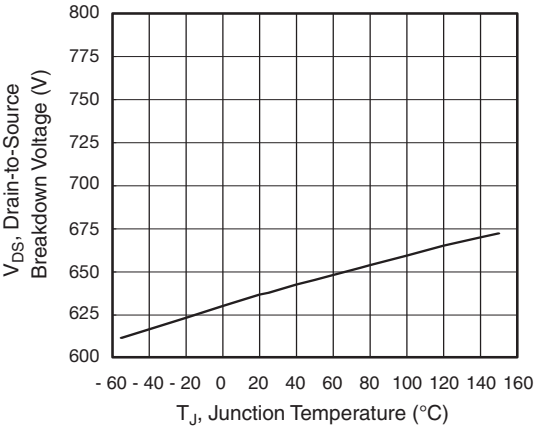


Fig. 10 - Temperature vs. Drain-to-Source Voltage

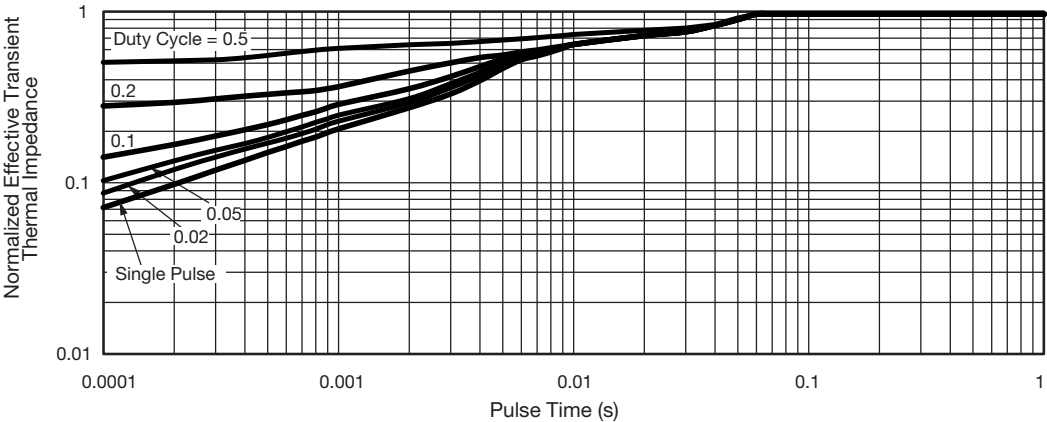


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

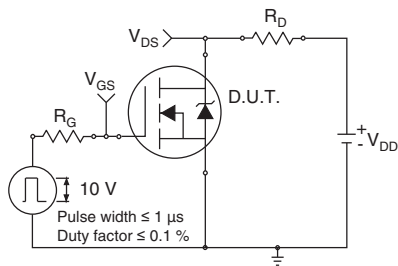


Fig. 12 - Switching Time Test Circuit

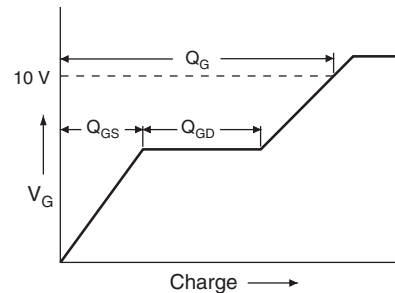


Fig. 16 - Basic Gate Charge Waveform

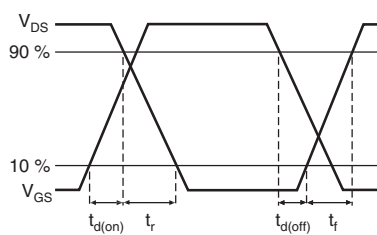


Fig. 13 - Switching Time Waveforms

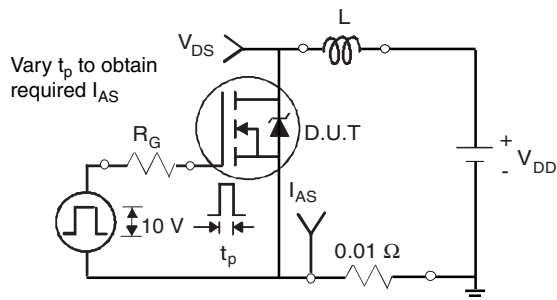


Fig. 14 - Unclamped Inductive Test Circuit

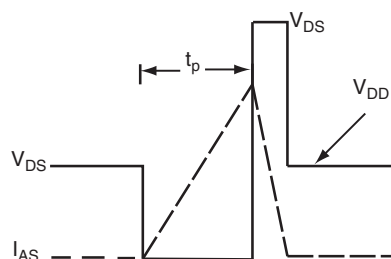


Fig. 15 - Unclamped Inductive Waveforms

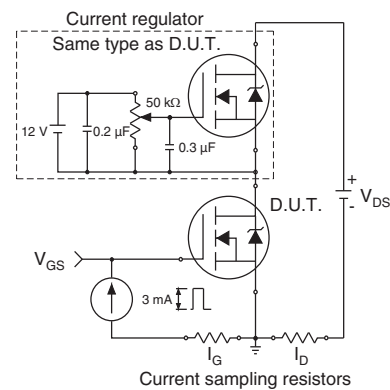
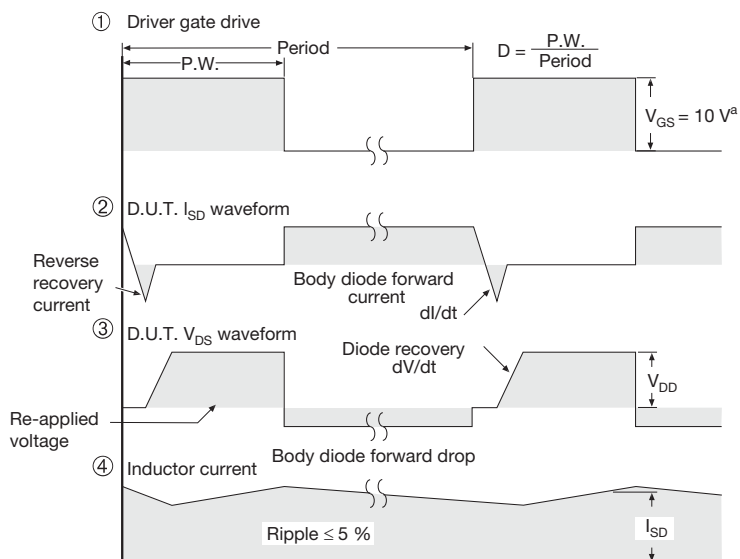
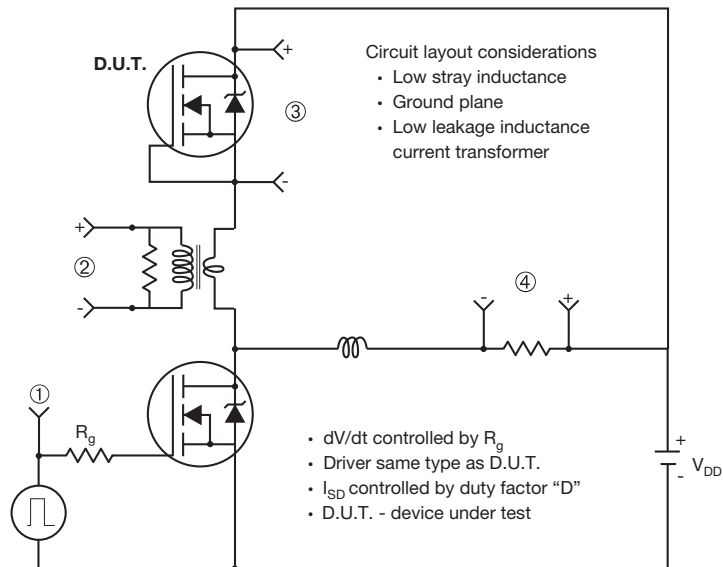


Fig. 17 - Gate Charge Test Circuit

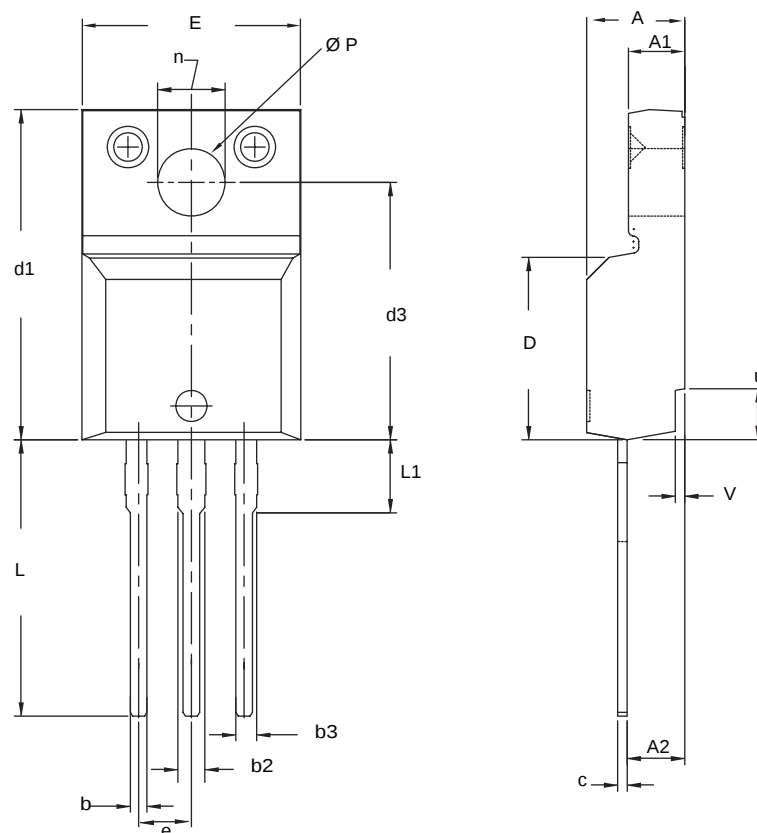
### Peak Diode Recovery $dV/dt$ Test Circuit



#### Note

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 18 - For N-Channel**

**TO-220 FULLPAK (HIGH VOLTAGE)**

| DIM. | MILLIMETERS |        | INCHES    |       |
|------|-------------|--------|-----------|-------|
|      | MIN.        | MAX.   | MIN.      | MAX.  |
| A    | 4.570       | 4.830  | 0.180     | 0.190 |
| A1   | 2.570       | 2.830  | 0.101     | 0.111 |
| A2   | 2.510       | 2.850  | 0.099     | 0.112 |
| b    | 0.622       | 0.890  | 0.024     | 0.035 |
| b2   | 1.229       | 1.400  | 0.048     | 0.055 |
| b3   | 1.229       | 1.400  | 0.048     | 0.055 |
| c    | 0.440       | 0.629  | 0.017     | 0.025 |
| D    | 8.650       | 9.800  | 0.341     | 0.386 |
| d1   | 15.88       | 16.120 | 0.622     | 0.635 |
| d3   | 12.300      | 12.920 | 0.484     | 0.509 |
| E    | 10.360      | 10.630 | 0.408     | 0.419 |
| e    | 2.54 BSC    |        | 0.100 BSC |       |
| L    | 13.200      | 13.730 | 0.520     | 0.541 |
| L1   | 3.100       | 3.500  | 0.122     | 0.138 |
| n    | 6.050       | 6.150  | 0.238     | 0.242 |
| Ø P  | 3.050       | 3.450  | 0.120     | 0.136 |
| u    | 2.400       | 2.500  | 0.094     | 0.098 |
| v    | 0.400       | 0.500  | 0.016     | 0.020 |

ECN: X09-0126-Rev. B, 26-Oct-09  
DWG: 5972

**Notes**

1. To be used only for process drawing.
2. These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
3. All critical dimensions should C meet  $C_{pk} > 1.33$ .
4. All dimensions include burrs and plating thickness.
5. No chipping or package damage.

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